METAL GLAZE™ GENERAL PURPOSE SURFACE MOUNT POWER RESISTOR





CHP SERIES



- Up to 2 watts
- 0.1 ohm to 2.2 megohm range
- Up to 1000 volts
- 150°C maximum operating temperature

CHP SPECIFICATIONS:

Size	Industry	IRC	Maximum	Working	Maximum	Resistance	Tolerance	TCR	Product
Code ¹	Footprint	Type	Power Rating	Voltage ²	Voltage	Range (ohms)3	(±%) ³	(ppm/°C) ³	Category
						0.1 to 0.99	1, 2, 5	100	Low Range
В	1206	CHP 1/8	1/4W @ 70°C	200	400	1.0 to 1.0 M	1, 2, 5	50, 100	Standard
	1200	0111 1/0		200	100	20 to 348K	0.25, 0.5	50, 100	Tight Tolerance
_			1/2W @ 70°C			0.1 to 0.99	1, 2, 5	100	Low Range
D	2010	CHP 1/2	1/2W @ 70 C	300	600	1.0 to 348K	1, 2, 5	50, 100	Standard
			1111 6 7000			0.1 to 0.99	1, 2, 5	100	Low Range
F	2512	CHP 1	1W @ 70°C	350	700	1.0 to 2.21M	1, 2, 5	50, 100	Standard
						20 to 348K	0.25, 0.5	50, 100	Tight Tolerance
Н	3610	CHP 2	2W @ 25°C	500	1000	0.2 to 0.99	1, 2, 5	100	Low Range
п	3010	CHP Z	1.33W @ 70°C	300	1000	1.0 to 2.21M	1, 2, 5	50, 100	Standard

¹See page 8 for product dimensions, recommended solder pads, and standard packaging. ²Not to exceed√PxR ³Consult factory for tighter TCR, tolerance, or resistance values.

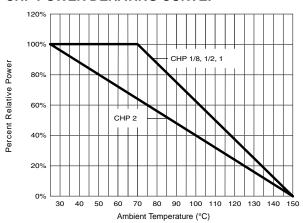
CHP PERFORMANCE CHARACTERISTICS:

Characteristics	Maximum Change	Test Method
Temperature Coefficient	As specified	MIL-R-55342E Par 4.7.9 (-55°C +125°C)
Thermal Shock	±0.5% +0.01 ohm	MIL-R-55342E Par 4.7.3 (-65°C +150°C, 5 cycles)
Low Temperature Operation	±0.25% +0.01 ohm	MIL-R-55342E Par 4.7.4 (-65°C @ working voltage)
Short Time Overload	±0.5% +0.01 ohm	MIL-R-55342E Par 4.7.5
	±1% for R>100K ohm	2.5 x√PxR for 5 seconds
High Temperature Exposure	±0.5% +0.01 ohm	MIL-R-55342E Par 4.7.6 (+150°C for 100 hours)
Resistance to Bonding Exposure	±0.25% 0.01 ohm	MIL-R-55342E Par 4.7.7 (Reflow soldered to board at 260°C for 10 seconds)
Solderability	95% minimum coverage	MIL-STD-202, Method 208 (245°C for 5 seconds)
Moisture Resistance	±0.5% +0.01 ohm	MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours)
Life Test	±0.5% +0.01 ohm	MIL-R-55342E Par 4.7.10 (2000 hour at 70°C intermittent)
Terminal Adhesion Strength	±1% +0.01 ohm	1200 gram push from underside of mounted chip for 60 seconds
_	no mechanical damage	
Resistance to Board Bending	±1% + 0.01 ohm	Chip mounted in center of 90mm long board, deflected 5mm so as to
	no mechanical damage	exert pull on chip contacts for 10 seconds

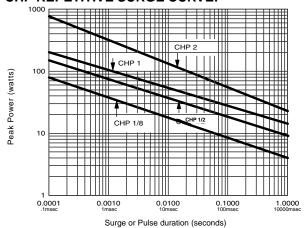




CHP POWER DERATING CURVE:

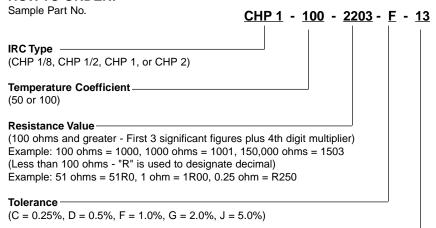


CHP REPETITIVE SURGE CURVE:



Note: Use for repetitive pulses where the average power dissipation is not to exceed the component rating at 70°C. Surge handling capacity for low-repetitive surges may be significantly greater than shown above. Contact factory for recommendations.

HOW TO ORDER:



(BLK = Bulk, 7=7" Reel, 13=13" Reel) *See page 8 for packaging details

Packaging Code*-

METAL GLAZE™ CYLINDRICAL SURFACE MOUNT RESISTORS





CHP SERIES

- GENERAL PURPOSE (pgs. 9, 10)

MRC SERIES

- HIGH POWER DENSITY (pgs. 11, 12)

MCHP SERIES

- HIGH RELIABILITY (pg. 13)

CHPT SERIES

- TEMPERATURE SENSITIVE (pgs. 14, 15)

ZCHP SERIES

- ZEROHM JUMPERS (pg. 16)

- High power up to 2 watts
- Low resistance down to 0.1 ohm at 1% tolerance
- High resistance up to 2.21 megohm
- Precision ±1% standard
- Low TCR ±100ppm/°C standard
- High voltage up to 1000 volts
- · Low inductance
- · Superior surge handling capability
- -55°C to +150°C operating temperature

- · Military versions
- Negative temperature coefficient version
- Zerohm jumpers
- Low-profile/minimum board real estate requirement
- · Superb solderability wave and reflow
- Established SPC & continuous improvement programs
- Excellent service and quality record/proven reliability
- High volume production capability



PRODUCT HISTORY:

The CHP Surface Mount Resistor Series is a member of the RG product family of precision Metal Glaze™ Resistors. The Metal Glaze™ technology, developed by IRC in 1960 to meet the stringent demands of the Military market, provides an unsurpassed combination of ruggedness, performance, and low cost. Since its development, IRC has supplied billions of units to meet the specific requirements not only of the Military, but also to all major users of resistive components requiring reliability, service, and quality at a reasonable price. Proven reliability of the Metal Glaze™ resistor family is supported by well over a billion unit hours of life testing with no failures.

The CHP Resistor was developed in 1980 by IRC to support the automotive move toward surface mount technology. The CHP uses the same highly reliable Metal Glaze™ technology and materials as its leaded counterpart. The termination and encapsulation have been modified to provide compatibility with surface mount technology. Since its development, the CHP has proven its reliability and service record by becoming a "World Class Product" supporting the surface mount needs of the Automotive, Computer, Instrumentation, Telecommunication, and other industrial electronics market.

PRODUCT DESCRIPTION:

The CHP is a precision surface mount power resistor. Its cylindrical shape is composed of a Metal Glaze™ resistive element fired onto a ceramic core with capless solder terminations. The simplicity of design and construction, provide a cost effective solution to common applications where reliability is a major concern, and also offer some unique features to surface mount technology.

The CHP uses a cylindrical high alumina ceramic for the core of the resistor. This substrate provides excellent thermal conductivity for maximum power dissipation in a minimum of board real estate. It also provides superb mechanical strength to easily withstand stresses presented during board assembly, mounting, and operation.

The Metal GlazeTM is composed of glass and metal particles which are fired onto the ceramic substrate at approximately 1000°C. This technology provides a resistive element that is impervious to environmental conditions without the need for an airtight encapsulation. The inherent ruggedness of this glaze can absorb higher voltage surges and overloads than "thin-film" counterparts.

To terminate the CHP, an electroless nickel barrier is applied to the termination area. Solder is then applied by hot-solder dipping. This technique provides reliable electrical continuity through the termination without the use of end-caps or weld joints. Unlike the typical "MELF", there is no "dog-bone" shape resulting from end-caps to interfere with "pick and place" accuracy. The solder termination is free of silver to provide superb solderability performance on both reflow and wave soldering processes.





CHP FAMILY STANDARD SIZES, SOLDER PADS AND PACKAGING:

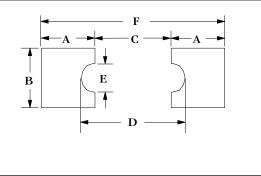
DIMENSIONS (Inches and (mm)):

	Industry		w C		
Size Code	Footprint	Actual Size	L	W	С
В	1206	(==)	0.128±0.007 (3.25±0.18)	0.057±0.006 (1.45±0.15)	0.020±0.010 (0.51±0.25)
С	1206	(==)	0.128±0.007 (3.25±0.18)	0.063±0.010 (1.60±0.25)	0.020±0.010 (0.51±0.25)
D	2010		0.200±0.010 (5.08±0.25)	0.079±0.006 (2.01±0.15)	0.030±0.010 (0.761±0.25)
Е	2010		0.200±0.010 (5.08±0.25)	0.105±0.006 (2.67±0.15)	0.040±0.015 (1.02±0.38)
F	2512		0.251±0.010 (6.38±0.25)	0.079±0.006 (2.01±0.15)	0.040±0.010 (1.02±0.25)
Н	3610		0.367±0.010 (9.32±0.25)	0.105±0.006 (2.67±0.15)	0.050±0.010 (1.27±0.25)

RECOMMENDED SOLDER PAD DIMENSIONS (REFLOW):

To ensure excellent solderability performance, IRC recommends the following pad design. This design will provide a large repeatable solder fillet to the CHP resistor on reflow processes and will provide maximum heat transfer to the PC board in high power applications. By placing the CHP on the solder paste while the paste is in the "tacky" state, the CHP will be held in position until solder reflow begins. The pad design then uses the surface tension of the molten solder to pull the component to the center of the solder pad. The placement of a via rising above the board level directly beneath the CHP is not recommended.

Size	Industry	Dimensions (Inches and (mm))						
Code	Footprint	Α	В	С	D	E	F	
B&C	1206	0.076 (1.93)	0.093 (2.36)	0.058 (1.47)	0.098 (2.49)	0.032 (0.81)	0.211 (5.36)	
D	2010	0.111 (2.82)	0.126 (3.20)	0.096 (2.44)	0.152 (3.86)	0.040 (1.02)	0.318 (8.08)	
E	2010	0.170 (4.32)	0.160 (4.06)	0.072 (1.83)	0.132 (3.35)	0.044 (1.12)	0.412 (10.46)	
F	2512	0.121 (3.07)	0.126 (3.20)	0.127 (3.23)	0.183 (4.65)	0.040 (1.02)	0.369 (9.37)	
Н	3610	0.170 (4.32)	0.160 (4.06)	0.213 (5.41)	0.273 (6.93)	0.044 (1.12)	0.553 (14.05)	



STANDARD REEL PACKAGING PER EIA-481:

Industry Footprint	Reel Diameter*	Quantity Per Reel	Carrier Tape Width	Component Pitch
	7"	2,500 max.		
1206	13"	10,000 max.	8mm	4mm
2010	7"	1,500 max.		_
2010	13"	5,000 max.	12mm	4mm
2010	7"	1,500 max.	12mm	4mm
	13"	5,000 max.	1211111	
2512	13"	5,000 max.	12mm	4mm
3610	7"	1,500 max.	24mm	4mm
	1206 2010 2010 2512	7" 1206 13" 2010 13" 2010 7" 13" 2010 13" 2512 13"	7" 2,500 max. 1206 13" 10,000 max. 2010 7" 1,500 max. 13" 5,000 max. 2010 7" 1,500 max. 13" 5,000 max. 2512 13" 5,000 max.	1206 7" 2,500 max. 8mm 1206 13" 10,000 max. 8mm 2010 7" 1,500 max. 12mm 2010 7" 1,500 max. 12mm 2010 7" 1,500 max. 12mm 2010 13" 5,000 max. 12mm 2010 13" 5,000 max. 12mm 2010 7" 1,500 max. 12mm 2010 7" 1,500 max. 12mm 2010 7" 1,500 max. 12mm 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010 2010

^{*} The 13" reel is considered standard and will be supplied unless otherwise specified.

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Click to view similar products for Thick Film Resistors - SMD category:

Click to view products by IRC manufacturer:

Other Similar products are found below:

CRCW04028R20JNEE CRCW06036K80FKEE CRG1206F1K58 CRL0603-FW-R700ELF M55342K06B6E19RWL RC1005F1072CS

RC1005F471CS RC1005F4751CS RCP0603W100RGED RCWP72251K47FKWB RLR05C7501GPB14 RLR07C5111FSBSL ERJ
IGMF1R00C ERJ-1GMF1R20C ERJ-1GMF2R55C ERJ-1GMF8R66C 25121WF1003T4E 25.501.3653.0 290-1.0M-RC 292-1.0M-RC 292
2.2K-RC 292-4.7K-RC 25121WF4700T4E 292-470K-RC 302-1.0M-RC CPG1206F10KC CRCW02011R00FXED CRCW060315K0FKEE

CRCW060320K5FKEE CRG0201F10K RCG0402150RFKED RCG04023K92FKED RCP2512B100RGWB RCWP110010R0FKS3

RCWP11002K00FKS3 RCWP12061K00FKS2 3520510RJT 352075KJT M55342K11B9E53RUL RMC16-102JT RMC1JPTE TR0603MR
075K1L 5-2176094-4 35202K7JT WF06Q1000FTL ERJ-S03J1R0V ERJ-S14J4R7U CHP2512L4R30GNT CPCC10270R0JE32

RCWP11001K00FKS3